

SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

LC87F2R04A CMOS IC 4K-byte FROM and 128-byte RAM integrated 8-bit 1-chip Microcontroller

Overview

The SANYO LC87F2R04A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 4K-byte flash ROM, 128-byte RAM, an Onchip-debugger, sophisticated 16-bit timers/counters (may be divided into 8-bit timers), two 8-bit timers with a prescaler, an asynchronous/synchronous SIO interface, a 12-bit/8-bit 8-channel AD converter, an internal reset and a 12-source 8-vector interrupt feature.

Features

- ■Flash ROM
 - Capable of on-board programming with wide range (2.2 to 5.5V) of voltage source.
 - Block-erasable in 128 byte units
 - Writable in 2-byte units
 - 4096×8 bits

■RAM

- 128×9 bits
- ■Minimum Bus Cycle
 - 83.3ns (12MHz at V_{DD}=2.7V to 5.5V)
 - 100ns (10MHz at V_{DD}=2.2V to 5.5V)

Note: The bus cycle time here refers to the ROM read speed.

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■Minimum Instruction Cycle Time

- 250ns (12MHz at V_{DD}=2.7V to 5.5V)
- 300ns (10MHz at V_{DD}=2.2V to 5.5V)

■Ports

• Normal withstand voltage I/O ports

Ports whose I/O direction can be designated in 1-bit units 11(P1n, P20, P21, P70)

Ports whose I/O direction can be designated in 4-bit units 8 (P0n)

• Dedicated oscillator ports/input ports 2 (CF1, CF2)

• Reset pin 1 (RES)

• Power pins 2 (V_{SS}1, V_{DD}1)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) \times 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)

+ 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)

■SIO

• SIO1: 8-bit asynchronous/synchronous serial interface

Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)

Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)

Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)

Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■AD Converter: 12 bits/8 bits × 8 channels

• 12/8 bits AD converter resolution selectable

■Remote Control Receiver Circuit (sharing pins with P73, INT3, and T0IN)

• Noise rejection function (noise filter time constant selectable from 1 tCYC/32 tCYC/128 tCYC)

■Watchdog Timer

- External RC watchdog timer
- Interrupt and reset signals selectable

■Interrupts

- 12 sources, 8 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
- 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3
5	00023H	H or L	ТОН
6	0002BH	H or L	None
7	00033H	H or L	None
8	0003BH	H or L	SIO1
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- ■Subroutine Stack Levels: 64levels (The stack is allocated in RAM.)
- ■High-speed Multiplication/Division Instructions

16 bits × 8 bits
24 bits × 16 bits
16 bits ÷ 8 bits
24 bits ÷ 16 bits
16 bits ÷ 8 bits
16 bits ÷ 16 bits
17 tCYC execution time
18 tCYC execution time
19 tCYC execution time
10 tCYC execution time
10 tCYC execution time
10 tCYC execution time
10 tCYC execution time
11 tCYC execution time
12 tCYC execution time
13 tCYC execution time
14 tCYC execution time
15 tCYC execution time
16 tCYC execution time
17 tCYC execution time
18 tCYC execution time
19 tCYC execution time
10 tCYC execution time

■Oscillation Circuits

• Internal oscillation circuits

Medium-speed RC oscillation circuit: For system clock (1MHz)
Multifrequency RC oscillation circuit: For system clock (8MHz)

• External oscillation circuits

Hi-speed CF oscillation circuit: For system clock, with internal Rf

■System Clock Divider Function

- Can run on low current.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

■Internal reset function

- Power-on reset (POR) function
 - 1) POR reset is generated only at power-on time.
 - 2) The POR release level can be selected from 8 levels (1.67V, 1.97V, 2.07V, 2.37V, 2.57V, 2.87V, 3.86V, and 4.35V) through option configuration.
- Low-voltage detection reset (LVD) function
 - 1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - 2) The use/disuse of the LVD function and the low voltage threshold level (7 levels: 1.91V, 2.01V, 2.31V, 2.51V, 2.81V, 3.79V, 4.28V).

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC and crystal oscillators automatically stop operation.
 - 2) There are four ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) System resetting by watchdog timer or low-voltage detection
 - (3) Having an interrupt source established at either INT0, INT1, INT2, INT4
 - * INTO and INT1 HOLD mode reset is available only when level detection is set.
 - (4) Having an interrupt source established at port 0.

■On-chip Debugger

- Supports software debugging with the IC mounted on the target board.
- Software break point setting for debugger.
- Stepwise execution on debugger.
- Real time RAM data monitoring function on debugger.

All the RAM data map can be monitored on screen when the program is running.

(The RAM & SFR data can be changed by screen patch when the program is running)

• Two channels of on-chip debugger pins are available to be compatible with small pin count devices. DBGP0 (P0), DBGP1 (P1)

■Data Security Function (flash versions only)

• Protects the program data stored in flash memory from unauthorized read or copy.

Note: This data security function does not necessarily provide absolute data security.

■Package Form

• MFP24S(300mil): Lead-/Halogen-free type

• SSOP24(225mil): Lead-/Halogen-free type

■Development Tools

• On-chip debugger: TCB87 TypeB+LC87F2R04A

: TCB87 TypeC (3 wire version) +LC87F2R04A

■Programming Boards

Package	Programming boards
MFP24S(300mil)	W87F2GM
SSOP24(225mil)	W87F2GS

■Flash ROM Programmer

Maker		Model	Supported Version	Device	
		AF9708			
	Single	AF9709/AF9709B/AF9709C	Rev 03.11 or later	LC87F2L08A	
Flash Support Group, Inc.		(including Ando Electric Co., Ltd. models)			
		AF9723/AF9723B(Main unit)			
(FSG)	Congod	(including Ando Electric Co., Ltd. models)	-	-	
	Ganged	AF9833(Unit)			
		(including Ando Electric Co., Ltd. models)	-	-	
Flash Support Group, Inc.		AF9101/AF9103(Main unit)			
(FSG)	Onboard	(FSG)	(Note 2)	İ	
+	single/ganged	SIB87(Interface driver)	(Note 2)	-	
SANYO (Note 1)		(SANYO)			
	Cia ala/aan aa d	SKK/SKK Type B	Application version		
Convo	Single/ganged	(SANYO FWS)	1.05 or later	LC87F2R04A	
Sanyo	Onboard	SKK-DBG Type B	Chip data version	LGO/FZRU4A	
	single/ganged	(SANYO FWS)	2.22 or later		

For information about AF-Series:

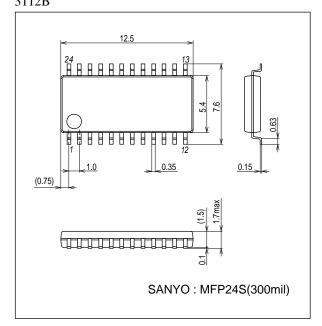
Flash Support Group, Inc. TEL: +81-53-459-1050 E-mail: sales@j-fsg.co.jp

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from SANYO (SIB87) together can give a PC-less, standalone on-board-programming capabilities.

Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or SANYO for the information.

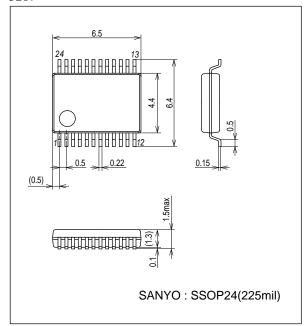
Package Dimensions

unit : mm (typ) 3112B

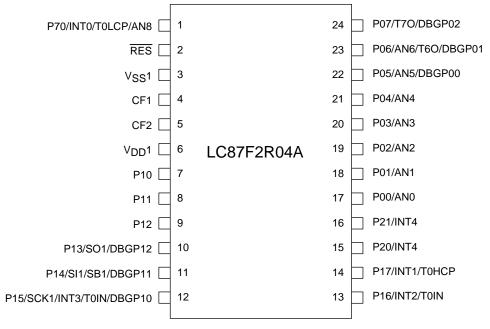


Package Dimensions

unit : mm (typ) 3287



Pin Assignment



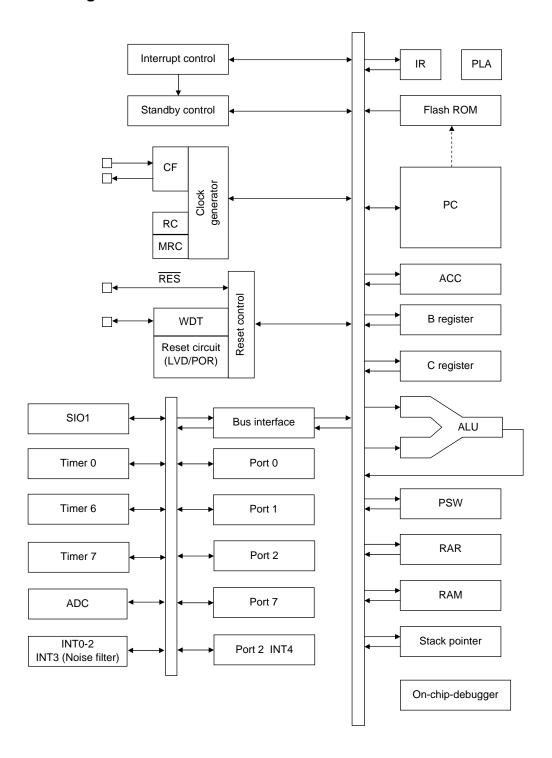
Top view

SANYO: MFP24S(300mil) "Lead-/Halogen-free Type" SANYO: SSOP24(225mil) "Lead-/Halogen-free Type"

MFP24S SSOP24	NAME
1	P70/INT0/T0LCP/AN8
2	RES
3	V _{SS} 1
4	CF1
5	CF2
6	V _{DD} 1
7	P10
8	P11
9	P12
10	P13/SO1/DBGP12
11	P14/SI1/SB1/DBGP11
12	P15/SCK1/INT3/T0IN/DBGP10

MFP24S SSOP24	NAME
13	P16/INT2/T0IN
14	P17/INT1/T0HCP
15	P20/INT4
16	P21/INT4
17	P00/AN0
18	P01/AN1
19	P02/AN2
20	P03/AN3
21	P04/AN4
22	P05/AN5/DBGP00
23	P06/AN6/T6O/DBGP01
24	P07/T7O/DBGP02

System Block Diagram



Pin Description

Pin Name	I/O			Des	scription			Option
V _{SS} 1	-	- power supply	pins					No
V _{DD} 1	-	+ power supply	pin					No
Port 0	I/O	• 8-bit I/O port						
P00 to P07		I/O specifiable	e in 4-bit units					
		· ·	ors can be turne	d on and off in 4	-bit units.			
		HOLD reset in	•					
		Port 0 interru						Yes
		 Pin functions P06: Timer 6 						
			toggle output					
			P06(AN6): AD co	onverter input				
) to P07(DBGP0	•	ugger 0 port			
Port 1	I/O	• 8-bit I/O port	,	,				
P10 to P17	1	I/O specifiable	e in 1-bit units					
		Pull-up resiste	ors can be turne	d on and off in 1	-bit units.			
		Pin functions						
		P13: SIO1 da	•					
			ta input/bus I/O					
			-	•	er)/timer 0 event	=	apture input	
			out/HOLD reset in out/HOLD reset in	•	nt input/timer 0L	capture input		Yes
		1) to P13(DBGP1	•	•			res
			owledge types	2). 011 01110 400	aggor i port			
					Rising &			
			Rising	Falling	Falling	H level	L level	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
2.10	1/0	0.13.1/0						
Port 2	I/O	2-bit I/O portI/O specifiable	e in 1-hit unite					
P20 to P21		-	ors can be turne	d on and off in 1	-hit units			
		Pin functions	oro carr bo tarrio	a o aa o				
		P20 to P21: II	NT4 input/HOLD	reset input/time	r 0L capture inpu	ıt/ timer 0H capt	ure input	
		Interrupt ackn	owledge types					Yes
			Dioina	Falling	Rising &	L lovel	Llovol	
			Rising	Falling	Falling	H level	L level	
		INT4	enable	enable	enable	disable	disable	
Port 7	I/O	• 1-bit I/O port						
P70		I/O specifiable						
		· ·	ors can be turne	d on and off in 1	-bit units.			
		Pin functions			-4 :464-1			
			out/HOLD reset ii D converter input	•	pture input/watch	aog timer outpu	τ	
		` '	owledge types					No
		Interrupt deki	lowicage types		Rising &			
			Rising	Falling	Falling	H level	L level	
		INT0	enable	enable	disable	enable	enable	
RES	I/O	External reset l	nput/internal res	et output				No
CF1	I		nator oscillator i					No
		• Pin function						
		General-purp	ose input port					
CF2	I/O	Ceramic reso	nator oscillator o	output pin			·	No
		 Pin function 						
		General-purp	ose input port					1

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable

Note 1: The control of the presence or absence of the programmable pull-up resistors for port 0 and the switching between low-and high-impedance pull-up connection is exercised in nibble (4-bit) units (P00 to 03 or P04 to 07).

User Option Table

Option Name	Option Type	Mask version *1	Flash Version	Option Selected in Units of	Option Selection
Port output type	P00 to P07	0	0	1 bit	CMOS
					Nch-open drain
	P10 to P17	0	0	1 bit	CMOS
					Nch-open drain
	P20 to P21	0	0	1 bit	CMOS
					Nch-open drain
Program start	-	×	0	-	00000h
address		*2			01E00h
Low-voltage	Detect function	0	0	-	Enable: Use
detection reset					Disable: Not Used
function	Detect level	0	0	-	7-level
Power-on reset function	Power-On reset level	0	0	-	8-level

^{*1:} Mask option selection-No change possible after mask is completed.

Recommended Unused Pin Connections

Port Name	Recommended Unused	Pin Connections
Port Name	Board	Software
P00 to P07	Open	Output low
P10 to P17	Open	Output low
P20 to P21	Open	Output low
P70	Open	Output low
CF1	Pulled low with a $100k\Omega$ resistor or less	General-purpose input port
CF2	Pulled low with a 100kΩ resistor or less	General-purpose input port

On-chip Debugger Pin Connection Requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "RD87 on-chip debugger installation manual" and "LC872000 series on-chip debugger pin connection requirements"

Notes on CF1 and CF2 Pins

• When using as general-purpose input ports Since the CF1 and CF2 pins are configured as CF oscillator pins at system reset time, it is necessary to add a current limiting resistor of $1k\Omega$ or greater to the CF2 pin in series when using them as general-purpose input pins.

^{*2:} Program start address of the mask version is 00000h.

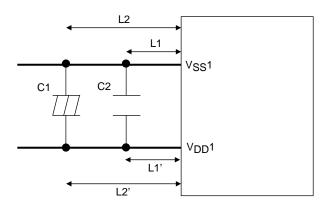
Differences between LC872G00 and LC872R00 Series.

		System Reset Time State	After System Reset is Released
Flash ROM version	CF1/XT1	Set high via the internal Rf resistor	CF oscillation state
LC87F2G08A	CF2/XT2	Set high	CF oscillation state
Mask ROM version	CF1/XT1	Set low via the internal Rf resistor	CF oscillation state
LC872G08A	CF2/XT2	Set low	CF oscillation state
Flash ROM version	CF1	Set low via the internal Rf resistor	CF oscillation state
LC87F2R04A Mask ROM version	CF2	High-impedance (OPEN)	CF oscillation state
LC872R04A		,	

Power Pin Treatment Recommendations (VDD1, VSS1)

Connect bypass capacitors that meet the following conditions between the V_{DD}1 and V_{SS}1 pins:

- Connect among the V_{DD}1 and V_{SS}1 pins and bypass capacitors C1 and C2 with the shortest possible heavy lead wires, making sure that the impedances between the both pins and the bypass capacitors are as possible (L1=L1', L2=L2').
- Connect a large-capacity capacitor C1 and a small-capacity capacitor C2 in parallel. The capacitance of C2 should approximately 0.1μF.



Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = 0V$

Doromotor		Cumbal	Din/Demorks	Din/Romarko Conditiono -		Specification			n	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
	ximum supply tage	V _{DD} max	V _{DD} 1			-0.3		+6.5		
Inp	out voltage	VI	CF1, CF2			-0.3		V _{DD} +0.3	V	
	out/output tage	VIO	Ports 0, 1, 2 P70			-0.3		V _{DD} +0.3		
ant	Peak output current	IOPH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-10				
High level output current	Mean output current (Note 1-1)	IOMH	Ports 0, 1, 2	CMOS output select Per 1 applicable pin		-7.5				
vel c	Total output	ΣΙΟΑΗ(1)	P10 to P14	Total of all applicable pins		-20				
High le	current	ΣΙΟΑΗ(2)	P15 to P17 Ports 0, 2	Total of all applicable pins		-20				
		ΣΙΟΑΗ(3)	Ports 0, 1, 2	Total of all applicable pins		-25				
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				20		
		IOPL(2)	P00, P01	Per 1 applicable pin				30	mA	
ţ		IOPL(3)	P70	Per 1 applicable pin				10		
Low level output current	Mean output current (Note 1-1)	IOML(1)	P02 to P07 Ports 1, 2	Per 1 applicable pin				15		
utput		IOML(2)	P00, P01	Per 1 applicable pin				20		
iel o		IOML(3)	P70	Per 1 applicable pin				7.5		
v le√	Total output	ΣIOAL(1)	P10 to P14	Total of all applicable pins				50		
Lo	current	ΣIOAL(2)	Ports 0, 2 P15 to P17	Total of all applicable pins				60		
		ΣIOAL(3)	Ports 0, 1, 2	Total of all applicable pins				70		
		ΣIOAL(4)	P70	Total of all applicable pins				7.5		
	wer ssipation	Pd max(1)	MFP24S(300mil))	Ta=-40 to +85°C Package only				129		
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				229	10/	
		Pd max(3)	SSOP24(225mil)	Ta=-40 to +85°C Package only				111	mW	
		Pd max(4)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				334		
	erating ambient mperature	Topr	_			-40		+85	90	
	orage ambient nperature	Tstg				-55		+125	°C	

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Allowable Operating Conditions at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

Parameter Paymbol Prin Pernants Prin									
Nome	Darameter	Cumbal	Din/Domorto	Conditions			Specifi	ication	
Vop(x) V	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Memory VHD VDD	Operating	V _{DD} (1)	V _{DD} 1	0.245μs ≤ tCYC ≤ 200μs		2.7		5.5	
Sustaining Supply voltage Find Fexor		V _{DD} (2)		0.294μs ≤ tCYC ≤ 200μs		2.2		5.5	
P70 port input Interrupt side	sustaining	VHD	V _{DD} 1	<u>-</u>		1.6			
Vh(3)	_	V _{IH} (1)	P70 port input/		2.2 to 5.5	0.3V _{DD} +0.7		V _{DD}	
timer side CF1 FES CF1 CF2 pin open System clock frequency division ratio=1/2 External system clock duty=50±5% External system clock d		V _{IH} (2)	Port 0		2.2 to 5.5	0.3V _{DD} +0.7		V_{DD}	
Vision V		V _{IH} (3)	_		2.2 to 5.5	0.9V _{DD}		V _{DD}	V
Low level input voltage Vil.(1)		V _{IH} (4)			2.2 to 5.5	0.75V _{DD}		VDD	
P70 port input Interrupt side	Low level		Ports 1, 2,		4.0 to 5.5				
VIL(2)	input voltage	12.	• •						
ViL(3)		V _{II} (2)	·		4.0 to 5.5	Vss		0.15Vnn+0.4	ĺ
Note 2-3 Port 70 watchdog timer side 2.2 to 5.5 VSS 0.8VpD-1.0					2.2 to 4.0				
Note 2-10 Note		V _{IL} (3)	_		2.2 to 5.5				
Instruction CYC (Note 2-2) CYC C		V _{II} (4)			2.2 to 5.5	Vee		0.25Vnn	
Cycle time (Note 2-1) Cycl	Instruction								
FEXCF	-	(Note 2-2)							μs
Frequency Frequency Fatio=1/1 External system clock duty=50±5% 2.2 to 5.5 0.1 10 MHz		FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12	
CF2 pin open	-			ratio=1/1	2.2 to 5.5	0.1		10	
See Fig. 1. 2.7 to 5.5 12				CF2 pin open System clock frequency division ratio=1/2	3.0 to 5.5	0.2		24.4	MHz
See Fig. 1. 2.2 to 5.5 10		FmCF(1)	CF1, CF2		2.7 to 5.5		12		
FmCF(3) CF1, CF2 4MHz ceramic oscillation. CF oscillation normal amplifier size selected. (CFLAMP=0) 2.2 to 5.5 4 See Fig. 1 4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1. 2.2 to 5.5 4 FmMRC Frequency variable RC oscillation. 1/2 frequency division ration. (RCCTD=0) (Note 2-4) 2.7 to 5.5 7.6 8.0 8.4	_	FmCF(2)	CF1, CF2		2.2 to 5.5		10		
4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1) See Fig. 1. FmMRC Frequency variable RC oscillation. 1/2 frequency division ration. (RCCTD=0) (Note 2-4)		FmCF(3)	CF1, CF2	CF oscillation normal amplifier size selected. (CFLAMP=0)	2.2 to 5.5		4		
1/2 frequency division ration. 2.7 to 5.5 7.6 8.0 8.4 (RCCTD=0) (Note 2-4)				4MHz ceramic oscillation. CF oscillation low amplifier size selected. (CFLAMP=1)	2.2 to 5.5		4		MHz
FmRC Internal medium-speed RC oscillation 2.2 to 5.5 0.5 1.0 2.0		FmMRC		1/2 frequency division ration.	2.7 to 5.5	7.6	8.0	8.4	
		FmRC		Internal medium-speed RC oscillation	2.2 to 5.5	0.5	1.0	2.0	

Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.

Note 2-4: When switching the system clock, allow an oscillation stabilization time of $100\mu s$ or longer after the multifrequency RC oscillator circuit transmits from the "oscillation stopped" to "oscillation enabled" state.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

Parameter	Symbol	Pin/Remarks	Conditions	_		Specifica	ation	1
i aiailletei	Gyllibol	i iivi\eiiiaiks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2 P70 RES	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.2 to 5.5			1	
	I _{IH} (2)	CF1	V _{IN} =V _{DD}	2.2 to 5.5			15	١,
Low level input current	I _{IL} (1)	(1) Ports 0, 1, 2 Output disabled P70 Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)		2.2 to 5.5	-1			μА
	I _{IL} (2)	CF1	V _{IN} =V _{SS}	2.2 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)		I _{OH} =-0.35mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.15mA	2.2 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)		I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (3)		I _{OL} =0.8mA	2.2 to 5.5			0.4	٧
	V _{OL} (4)	P70	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (5)		I _{OL} =0.8mA	2.2 to 5.5			0.4	
	V _{OL} (6)	P00, P01	I _{OL} =25mA	4.5 to 5.5			1.5	
	V _{OL} (7)		I _{OL} =4mA	2.7 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =2mA	2.2 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2 P70	V _{OH} =0.9V _{DD} When Port 0 selected	4.5 to 5.5	15	35	80	
	Rpu(2)	170	low-impedance pull-up.	2.2 to 4.5	18	50	230	
	Rpu(3)	Port 0	V _{OH} =0.9V _{DD} When Port 0 selected high-impedance pull-up.	2.2 to 5.5	100	210	400	kΩ
Hysteresis voltage	VHYS(1)	Ports 1, 2		2.7 to 5.5		0.1V _{DD}		
	VHYS(2)	P70 RES		2.2 to 5.5		0.07V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.2 to 5.5		10		pF

Serial I/O Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$ (Note 4)

	Parameter	Doromotor	Symbol	Pin/	Conditions		Specification			
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig. 5.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.2 to 5.5	1			10)(0
Serial clock	u	High level pulse width	tSCKH(3)				1			tCYC
Serial	ock	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig. 5.		2			
	Output clock	Low level pulse width	tSCKL(4)			2.2 to 5.5		1/2		tSCK
	ō	High level pulse width	tSCKH(4)	SCKH(4)			1/2			took
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK. See Fig. 5.	004.55	0.05			
Serial	Da	ata hold time	thDI(2)			2.2 to 5.5	0.05			
Serial output	Output delay time		tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.	2.2 to 5.5			(1/3)tCYC +0.08	μѕ

Note 4: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at Ta = -40°C to +85°C, $V_SS1 = 0V$

Danamatan	Oh. al	Dia/Damanta	Odition			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tPIH(1) tPIL(1)	INT0(P70), INT1(P17), INT2(P16), INT4(P20 to P21),	Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled.	2.2 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P15) when noise filter time constant is 1/1	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.2 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P15) when noise filter time constant is 1/32	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.2 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P15) when noise filter time constant is 1/128	Interrupt source flag can be set. Event inputs for timer 0 are enabled.	2.2 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	2.2 to 5.5	200			μs

AD Converter Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

12bits AD Converter Mode

Parameter	Cumhal	Pin/Remarks	Conditions			Specific	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		12		bit
Absolute	ET	AN6(P06),	(Note 6-1)	2.7 to 5.5			±16	- 00
accuracy		AN8(P70)		2.4 to 5.5			±20	LSB
Conversion time	ime TCAD • Se		See Conversion time calculation	4.0 to 5.5	32		115	
			formulas.	2.7 to 5.5	64		115	μs
			(Note 6-2)	2.4 to 5.5	410		425	
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V_{DD}	٧
Analog port	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μА

8bits AD Converter Mode

Parameter	Symbol	Pin/Remarks	Conditions			Specifi	cation	
Farameter	Symbol	FIII/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		8		bit
Absolute accuracy	ET	AN6(P06) AN8(P70)	(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion time	TCAD		See Conversion time calculation	4.0 to 5.5	20		90	
			formulas.	2.7 to 5.5	40		90	μs
			(Note 6-2)	2.4 to 5.5	250		265	
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	٧
Analog port	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	4
input current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μА

Conversion time calculation formulas:

12bits AD Converter Mode: TCAD(Conversion time) = $((52/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$ 8bits AD Converter Mode: TCAD(Conversion time) = $((32/(AD \text{ division ratio}))+2)\times(1/3)\times tCYC$

External oscillation	Operating supply voltage range	System division ratio	Cycle time	AD division ratio	AD conversion time (TCAD)		
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD	
CE 42MH=	4.0V to 5.5V	1/1	250ns	1/8	34.8µs	21.5μs	
CF-12MHz	3.0V to 5.5V	1/1	250ns	1/16	69.5μs	42.8μs	
CF-10MHz	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8μs	
CF-10IVIH2	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4μs	
OF ANIL-	3.0V to 5.5V	1/1	750ns	1/8	104.5μs	64.5μs	
CF-4MHz	2.4V to 5.5V	1/1	750ns	1/32	416.5μs	256.5μs	

Note 6-1: The quantization error $(\pm 1/2LSB)$ must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Power-on Reset (POR) Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

						Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	Conditions Option selected voltage		typ	max	unit
POR release	PORRL		Select from option.	1.67V	1.55	1.67	1.79	
voltage			(Note 7-1)	1.97V	1.85	1.97	2.09	
				2.07V	1.95	2.07	2.19	
				2.37V	2.25	2.37	2.49	
				2.57V	2.45	2.57	2.69	
				2.87V	2.75	2.87	2.99	V
				3.86V	3.73	3.86	3.99	
				4.35V	4.21	4.35	4.49	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 7-2)			0.7	0.95	
Power supply rise time	PORIS		Power supply rise time from 0V to 1.6V.				100	ms

Note7-1: The POR release level can be selected out of 4 levels only when the LVD reset function is disabled.

Note7-2: POR is in an unknown state before transistors start operation.

Low Voltage Detection Reset (LVD) Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

		<u> </u>	<u> </u>				55	
						Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min	typ	max	unit
LVD reset Voltage	LVDET		Select from option.	1.91V	1.81	1.91	2.01	
(Note 8-2)			(Note 8-1)	2.01V	1.91	2.01	2.11	
			(Note 8-3)	2.31V	2.21	2.31	2.41	
			See Fig. 8.	2.51V	2.41	2.51	2.61	V
				2.81V	2.71	2.81	2.91	
				3.79V	3.69	3.79	3.89	
				4.28V	4.18	4.28	4.38	
LVD hysteresis	LVHYS			1.91V		55		
width				2.01V		55		
				2.31V		55		
				2.51V		55		mV
				2.81V		60		
				3.79V		65		
				4.28V		65		
Detection voltage unknown state	LVUKS		• See Fig. 8. (Note 8-4)			0.7	0.95	٧
Low voltage detection minimum Width (Reply sensitivity)	TLVDW		• LVDET-0.5V • See Fig. 9.		0.2			ms

Note8-1: The LVD reset level can be selected out of 3 levels only when the LVD reset function is enabled.

Note8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note8-4: LVD is in an unknown state before transistors start operation.

Consumption Current Characteristics at Ta = -40 °C to +85 °C, $V_{SS}1 = 0V$

Parameter	Symbol	Pin/	Conditions			Specif	ication	
Farameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1	FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal medium speed RC oscillation	2.7 to 5.5		6.1	10	
(Note 9-1) (Note 9-2)			stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		3.7	6.4	
	IDDOP(2)		FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal medium speed RC oscillation	2.2 to 5.5		5.3	9.1	
			stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 3.6		3.4	5.8	
	IDDOP(3)		FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal medium speed RC oscillation	2.2 to 5.5		2.6	5.5	
	IDDOD(4)		stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 3.6		1.9	3.4	
	IDDOP(4)	CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	2.2 to 5.5		1.1	2.1	mA	
			Internal medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.56	1.1	
	IDDOP(5)		External FmCF oscillation stopped. System clock set to internal medium speed RC oscillation.	2.2 to 5.5		0.47	1.2	
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio	2.2 to 3.6		0.28	0.65	
	IDDOP(6)		External FmCF oscillation stopped. Internal medium speed RC oscillation stopped.	2.7 to 5.5		4.2	8.1	
			System clock set to 8MHz with frequency variable RC oscillation.(RCCTD=0) 1/1 frequency division ratio. 2			3.3	5.6	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

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Parameter	Symbol	Pin/	Conditions			Specit	fication	
i alametei	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
HALT mode consumption current (Note 9-1)	IDDHALT(1)	V _{DD} 1	HALT mode FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal medium speed RC oscillation	2.7 to 5.5		2.3	4.1	
(Note 9-2)			stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.7 to 3.6		1.2	1.9	
	IDDHALT(2)		HALT mode FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side Internal medium speed RC oscillation	2.2to 5.5		1.9	3.4	
			stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 3.6		1.0	1.6	
	IDDHALT(3)		HALT mode FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side Internal medium speed RC oscillation	2.2 to 5.5		1.3	2.5	
			stopped. • Frequency variable RC oscillation stopped. • 1/1 frequency division ratio	2.2 to 3.6		0.53	1.0	
	IDDHALT(4)		HALT mode CF oscillation low amplifier size selected. (CFLAMP=1) FmCF=4MHz ceramic oscillation mode	2.2 to 5.5		0.80	1.5	mA
			System clock set to 4MHz side Internal medium speed RC oscillation stopped. Frequency variable RC oscillation stopped. 1/4 frequency division ratio	2.2 to 3.6		0.31	0.62	
	IDDHALT(5)		HALT mode External FmCF oscillation stopped. System clock set to internal medium speed	2.2 to 5.5		0.28	0.73	
			RC oscillation • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	2.2 to 3.6		0.14	0.36	
	IDDHALT(6)		HALT mode External FmCF oscillation stopped. Internal medium speed RC oscillation stopped.	2.7 to 5.5		1.3	2.7	
			System clock set to 8MHz with frequency variable RC oscillation. (RCCTD=0) 1/1 frequency division ratio.	2.7 to 3.6		0.93	1.8	
HOLD mode consumption	IDDHOLD(1)	V _{DD} 1	HOLD mode CF1=V _{DD} or open (External clock mode)	2.2 to 5.5		0.03	25	
current			C TDD or opon (External block mode)	2.2 to 3.6		0.02	5.9	
(Note 9-1) (Note 9-2)	IDDHOLD(2)		HOLD mode CF1=V _{DD} or open (External clock mode)	5.0		0.03	1.2	
(• Ta=-10 to +50°C	3.3		0.02	0.56	
				2.5		0.01	0.40	
	IDDHOLD(3)		HOLD mode • CF1=V _{DD} or open (External clock mode)	2.2 to 5.5		3.0	29	μА
			2.2 to 3.6		2.3	10	-	
	IDDHOLD(4)	LVD option selected HOLD mode CE1-Vpp or open (External class)		5.0		3.0	7.3	
			CF1=V _{DD} or open (External clock mode) Ta=-10 to +50°C	3.3		2.3	3.4	
			LVD option selected	2.5		2.0	2.9	

Note9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note9-2: The consumption current values do not include operational current of LVD function if not specified.

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = 0V$

Parameter	er Symbol Pin/Remarks Conditions		Conditions		Specification			
Parameter			Conditions	V _{DD} [V]	min	typ	max	unit
Onboard	IDDFW(1)	V _{DD} 1	Only current of the flash block.					
programming				2.2 to 5.5		5	10	mA
current								
Programming	tFW(1)		Erasing time	0.04- 5.5		20	30	ms
time	tFW(2)		Programming time	2.2 to 5.5		40	60	μs

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a SANYO-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

• CF oscillation normal amplifier size selected (CFLAMP=0)

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Nominal		0		Circuit (Constant		Operating	Oscillation Stabilization Time		D l .
Frequency	Type	Oscillator Name	C1	C2	Rf	Rd	Voltage Range [V]	typ	max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[,]	[ms]	[ms]	
12MHz	SMD	CSTCE12M0G52-R0	(10)	(10)	Open	680	2.2 to 5.5	0.1	0.5	
1 Z IVII 1Z	OIVID	0010E12IVI0002-10	(10)	(10)	Open	1.0k	2.5 to 5.5	0.1	0.5	
	SMD	CSTCE10M0G52-R0	(10)	(10)	Open	680	2.0 to 5.5	0.1	0.5	
10MHz	SIVID	CSTCL TOWNOGSZ-KO	(10)	(10)	Open	1.0k	2.1 to 5.5	0.1	0.5	
TOWINZ	LEAD	CSTLS10M0G53-B0	(15)	(15)	Open	680	2.2 to 5.5	0.1	0.5	
	LEAD	C31L310M0G33-B0	(13)	(13)	Open	1.0k	2.4 to 5.5	0.1	0.5	
	SMD	CSTCE8M00G52-R0	(40)	(10)	Open	1.0k	1.9 to 5.5	0.1	0.5	
8MHz			(10)	(10)	Open	1.5k	2.0 to 5.5	0.1	0.5	
OIVITIZ	LEAD	CSTLS8M00G53-B0	(15)	(15)	Open	1.0k	2.0 to 5.5	0.1	0.5	Internal
	LEAD	C31L36W00G33-B0	(13)	(13)	Open	1.5k	2.2 to 5.5	0.1	0.5	C1,C2
	SMD	CSTCR6M00G53-R0	(4.5)	(4.5)	Open	1.5k	1.9 to 5.5	0.1	0.5	
6MHz	SIVID	CSTCR6W00G53-R0	(15)	(15)	Open	2.2k	2.0 to 5.5	0.1	0.5	
OIVITZ	LEAD	CSTLS6M00G53-B0	(4.5)	(4.5)	Open	1.5k	2.0 to 5.5	0.1	0.5	
	LEAD	CSTLS6W00G53-B0	(15)	(15)	Open	2.2k	2.1 to 5.5	0.1	0.5	
	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	1.5k	1.8 to 5.5	0.2	0.6	
4041.1-	SIVID	C31 CR4W00G53-R0	(15)	(15)	Open	3.3k	1.9 to 5.5	0.2	0.6	
4MHz	LEAD	CCTI CAMOOCES DO	(4.5)	(4.5)	Open	1.5k	1.8 to 5.5	0.2	0.6	
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	3.3k	1.9 to 5.5	0.2	0.6	

• CF oscillation low amplifier size selected (CFLAMP=1)

■MURATA

Nominal Frequency	Туре	Oscillator Name	Circuit Constant				Operating	Oscillation Stabilization Time		
			C1 [pF]	C2 [pF]	Rf [Ω]	Rd [Ω]	Voltage Range [V]	typ [ms]	max [ms]	Remarks
4MHz	SMD	CSTCR4M00G53-R0	(15)	(15)	Open	1.0k	1.9 to 5.5	0.2	0.6	Internal C1,C2
					Open	2.2k	2.1 to 5.5	0.2	0.6	
		CSTCR4M00G53095-R0	(15)	(15)	Open	1.0k	1.8 to 5.5	0.2	0.6	
					Open	2.2k	1.9 to 5.5	0.2	0.6	
	LEAD	CSTLS4M00G53-B0	(15)	(15)	Open	1.0k	2.0 to 5.5	0.2	0.6	
					Open	2.2k	2.1 to 5.5	0.2	0.6	
		CSTLS4M00G53095-B0	(15)	(15)	Open	1.0k	1.8 to 5.5	0.2	0.6	
					Open	2.2k	1.9 to 5.5	0.2	0.6	

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 3).

- Time till the oscillation gets stabilized after the CPU reset state is released.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed.
- Till the oscillation gets stabilized after the HOLD mode is reset. (Notes on the implementation of the oscillator circuit)
- Oscillation is influenced by the circuit pattern layout of printed circuit board. Place the oscillation-related components as close to the CPU chip and to each other as possible with the shortest possible pattern length.
- Keep the signal lines whose state changes suddenly or in which large current flows as far away from the oscillator circuit as possible and make sure that they do not cross one another.
- Be sure to insert a current limiting resistor (Rd) so that the oscillation amplitude never exceeds the input voltage level that is specified as the absolute maximum rating.
- The oscillator circuit constants shown above are sample characteristic values that are measured using the SANYO-designated oscillation evaluation board. Since the accuracy of the oscillation frequency and other characteristics vary according to the board on which the IC is installed, it is recommended that the user consult the resonator vendor for oscillation evaluation of the IC on a user's production board when using the IC for applications that require high oscillation accuracy. For further information, contact your resonator vendor or SANYO Semiconductor sales representative serving your locality.
- It must be noted, when replacing the flash ROM version of a microcontroller with a mask ROM version, that their operating voltage ranges may differ even when the oscillation constant of the external oscillator is the same.

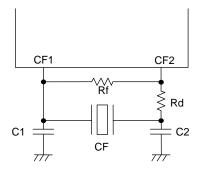
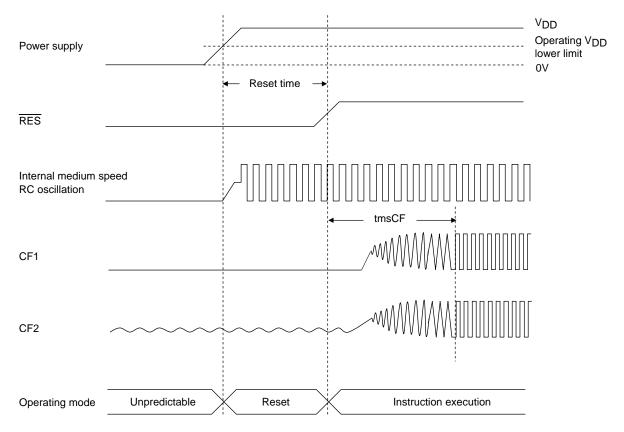


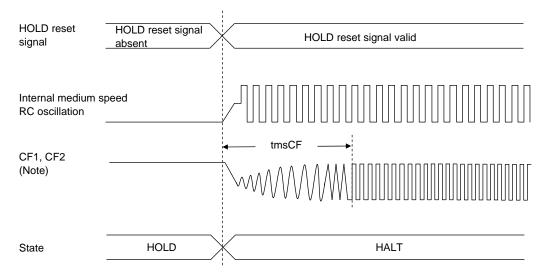
Figure 1 CF Oscillator Circuit



Figure 2 AC Timing Measurement Point



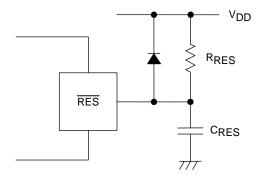
Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Note: External oscillation circuit is selected.

Figure 3 Oscillation Stabilization Times



Note:

External circuits for reset may vary depending on the usage of POR and LVD. Please refer to the user's manual for more information..

Figure 4 Reset Circuit

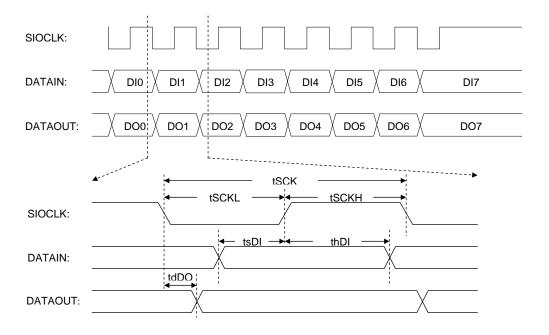


Figure 5 Serial I/O Output Waveforms

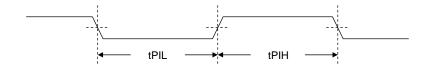


Figure 6 Pulse Input Timing Signal Waveform

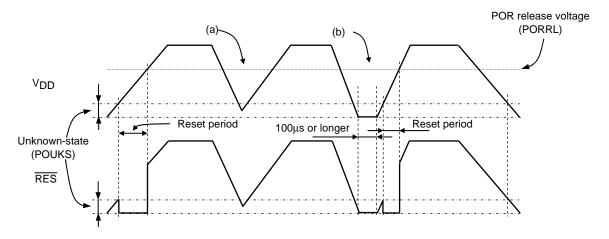


Figure 7 Waveform observed when only POR is used (LVD not used) (RESET pin: Pull-up resistor RRES only)

- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.

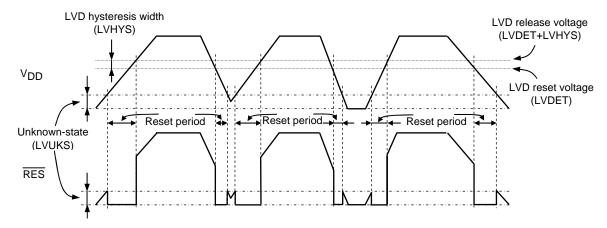


Figure 8 Waveform observed when both POR and LVD functions are used (RESET pin: Pull-up resistor R_{RES} only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

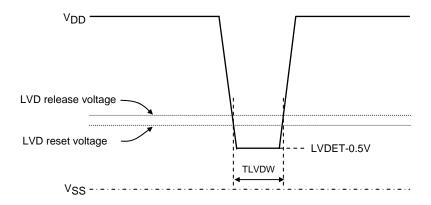


Figure 9 Low voltage detection minimum width (Example of momentary power loss / Voltage variation waveform)

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